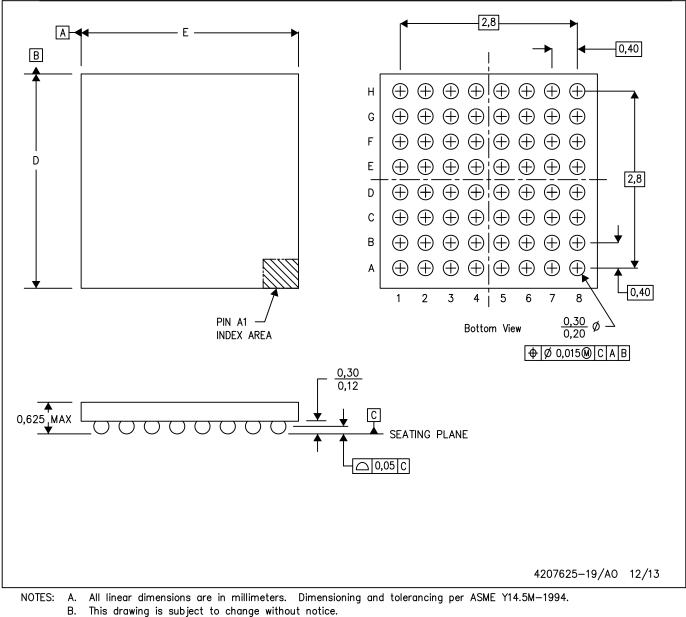
YFF (R-XBGA-N64)

DIE-SIZE BALL GRID ARRAY



C. NanoFree™ package configuration.

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